

Terms & Conditions

Terms and conditions governing submissions to the Texas Instruments MCU Design Challenge 2014 (TIMDC)

Please read and accept the following terms and conditions prior to making any submissions or providing any ideas or materials to Texas Instruments (India) Private Limited (TI) in respect of the Texas Instruments MCU Design Challenge 2014 (TIMDC). All submissions made for the TIMDC are subject to these terms and conditions and by making the submission, you would be deemed to have unconditionally acknowledged and accepted the same:

- Participant entries will be judged for:
 - Innovation / Creativity
 - Design optimization
 - Number of TI products/parts incorporated in the design
 - Technical Merit
 - Utility of application
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- You shall ensure that you comply with all applicable laws and the policies and procedures of your employer in making the submissions for the TIMDC. TI has no duty to check your submissions for such compliance and you alone shall be responsible for all consequences of failing to adhere to the pertinent laws, policies or procedures.
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- TI's decision in respect of any matter concerning the TIMDC and any subsequent interview or interaction shall be final and binding upon you and you shall accept the same without demur. In any event, all disputes amongst TI and you or any third parties claiming through you shall be subject to the sole jurisdiction of the courts at Bangalore, India.
- Direct employees of the Sponsor, the Challenge Administrator, or their affiliates, advertising, promotion, production agencies, members of their immediate families, or those with whom they are domiciled are not eligible to enter the TIMDC.

In the event that any of the above terms are unacceptable to you, please refrain from participating in TIMDC.

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Mailing Address: Texas Instruments, Post Office Box 655303, Dallas, Texas 75265
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